L Number	Hits	Search Text	DB	Time stamp
1	27321	electrophoretic\$4	USPAT;	2002/08/15
_		-	US-PGPUB;	09:25
}	•		EPO; JPO;	
ŀ			DERWENT;	
<u> </u>	4.400505	3 40	IBM_TDB USPAT;	2002/08/15
8	1483537	polymer\$2	US-PGPUB;	09:26
ŧ.			EPO; JPO;	09.20
			DERWENT;	
			IBM TDB	
15	157995	polymeriz\$3	USPĀT;	2002/08/15
			US-PGPUB;	09:27
			EPO; JPO;	
			DERWENT;	
	0500	J	IBM_TDB USPAT;	2002/08/15
22	2520	electrophoretic\$4 same polymer\$2	US-PGPUB;	09:28
· ·			EPO; JPO;	03.23
			DERWENT;	
1			IBM_TDB	
29	1769	electrophoretic\$4 with polymer\$2	USPAT;	2002/08/15
1			US-PGPUB;	09:28
			EPO; JPO;	
			DERWENT; IBM TDB	
36	42	(electrophoretic\$4 with polymer\$2) same	USPAT;	2002/08/15
36	42	polymeriz\$3	US-PGPUB;	09:36
		polymorizato	EPO; JPO;	
			DERWENT;	!
			IBM_TDB	
43	444	(electrophoretic\$4 with polymer\$2) and	USPAT;	2002/08/15
		(polymeriz\$3 or cure or curing)	US-PGPUB; EPO; JPO;	09:37
			DERWENT;	
			IBM TDB	
50	314	((electrophoretic\$4 with polymer\$2) and	USPAT;	2002/08/15
		(polymeriz\$3 or cure or curing)) and	US-PGPUB;	09:37
		metal	EPO; JPO;	
	1		DERWENT;	
59	1469	(gold or au or nickel or ni or tin or sn	USPAT;	2002/08/15
139	1409	or platinum or pt or cr or chromium) with	US-PGPUB;	10:30
	1	(sputter\$ and electroplat\$3)	EPO; JPO;	
1			DERWENT;	
			IBM_TDB	0000 (00 (55
66	1221	(cu or copper) with (sputter\$ and	USPAT;	2002/08/15
		electroplat\$3)	US-PGPUB; EPO; JPO;	10:30
			DERWENT;	
			IBM TDB	
80	573	(cu or copper) with (sputter\$ with	USPAT;	2002/08/15
		electroplat\$3)	US-PGPUB;	10:31
			EPO; JPO;	
1	1		DERWENT;	
73	683	(gold or au or nickel or ni or tin or sn	IBM_TDB USPAT;	2002/08/15
'3	603	or platinum or pt or cr or chromium) with	US-PGPUB;	10:31
		(sputter\$ with electroplat\$3)	EPO; JPO;	.
		• • • •	DERWENT;	
	1		IBM_TDB	0000/00/55
87	199		USPAT;	2002/08/15
	1	electroplat\$3)) with ((gold or au or nickel or ni or tin or sn or platinum or	US-PGPUB; EPO; JPO;	10:32
		pt or cr or chromium) with (sputter\$ with	DERWENT;	
		electroplat\$3))	IBM TDB	

		•		
94	1 (((cu or copper) with (sputter\$ with	USPAT;	2002/08/15	
	electroplat\$3)) with ((gold or au or	US-PGPUB;	10:32	
	nickel or ni or tin or sn or platinum or	EPO; JPO;		
	pt or cr or chromium) with (sputter\$ with	DERWENT;		
	electroplat\$3))) and electrophoretic\$4	IBM TDB		

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